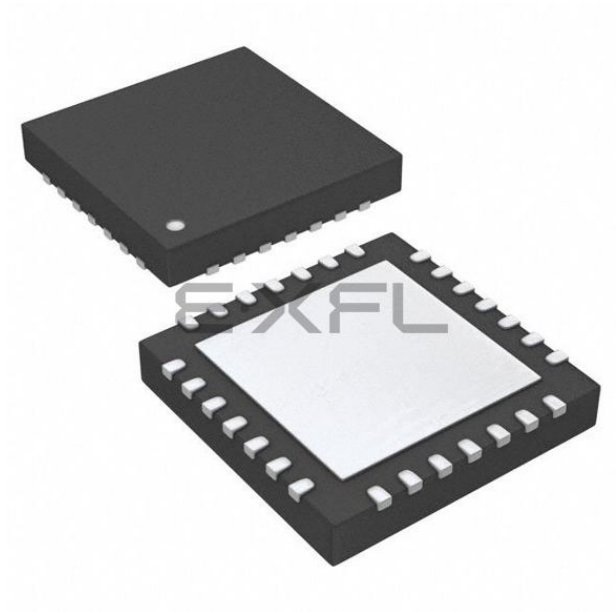

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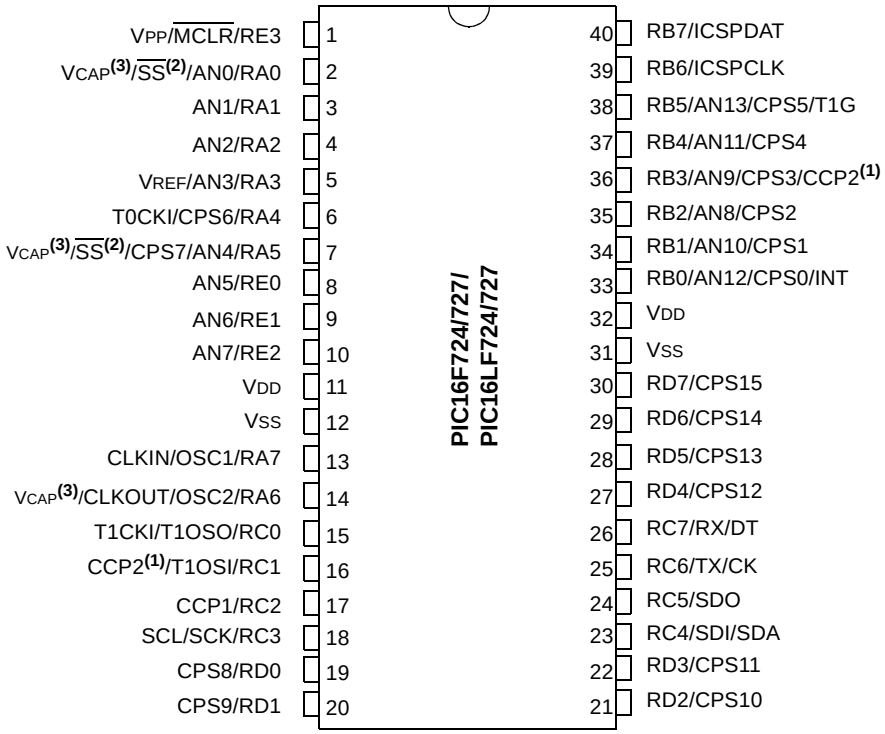
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf722-e-ml

Pin Diagrams – 40-PIN PDIP (PIC16F724/727/PIC16LF724/727)



Note 1: CCP2 pin location may be selected as RB3 or RC1.
2: SS pin location may be selected as RA5 or RA0.
3: PIC16F724/727 devices only.

TABLE 1-1: PIC16(L)F722/3/4/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RD3/CPS11	RD3	ST	CMOS	General purpose I/O.
	CPS11	AN	—	Capacitive sensing input 11.
RD4/CPS12	RD4	ST	CMOS	General purpose I/O.
	CPS12	AN	—	Capacitive sensing input 12.
RD5/CPS13	RD5	ST	CMOS	General purpose I/O.
	CPS13	AN	—	Capacitive sensing input 13.
RD6/CPS14	RD6	ST	CMOS	General purpose I/O.
	CPS14	AN	—	Capacitive sensing input 14.
RD7/CPS15	RD7	ST	CMOS	General purpose I/O.
	CPS15	AN	—	Capacitive sensing input 15.
RE0/AN5	RE0	ST	CMOS	General purpose I/O.
	AN5	AN	—	A/D Channel 5 input.
RE1/AN6	RE1	ST	CMOS	General purpose I/O.
	AN6	AN	—	A/D Channel 6 input.
RE2/AN7	RE2	ST	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7 input.
RE3/$\overline{MCLR}$/V_{PP}	RE3	TTL	—	General purpose input.
	$\overline{MCLR}$	ST	—	Master Clear with internal pull-up.
	V_{PP}	HV	—	Programming voltage.
V_{DD}	V_{DD}	Power	—	Positive supply.
V_{SS}	V_{SS}	Power	—	Ground reference.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C
HV = High Voltage XTAL = Crystal levels

Note: The PIC16F722/3/4/6/7 devices have an internal low dropout voltage regulator. An external capacitor must be connected to one of the available V_{CAP} pins to stabilize the regulator. For more information, see **Section 5.0 "Low Dropout (LDO) Voltage Regulator"**. The PIC16LF722/3/4/6/7 devices do not have the voltage regulator and therefore no external capacitor is required.

2.0 MEMORY ORGANIZATION

2.1 Program Memory Organization

The PIC16(L)F722/3/4/6/7 has a 13-bit program counter capable of addressing a 2K x 14 program memory space for the PIC16F722/LF722 (0000h-07FFh), a 4K x 14 program memory space for the PIC16F723/LF723 and PIC16F724/LF724 (0000h-0FFFh) and an 8K x 14 program memory space for the PIC16F726/LF726 and PIC16F727/LF727 (0000h-1FFFh). Accessing a location above the memory boundaries for the PIC16F722/LF722 will cause a wrap-around within the first 2K x 14 program memory space. Accessing a location above the memory boundaries for the PIC16F723/LF723 and PIC16F724/LF724 will cause a wrap-around within the first 4K x 14 program memory space. The Reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F722/LF722

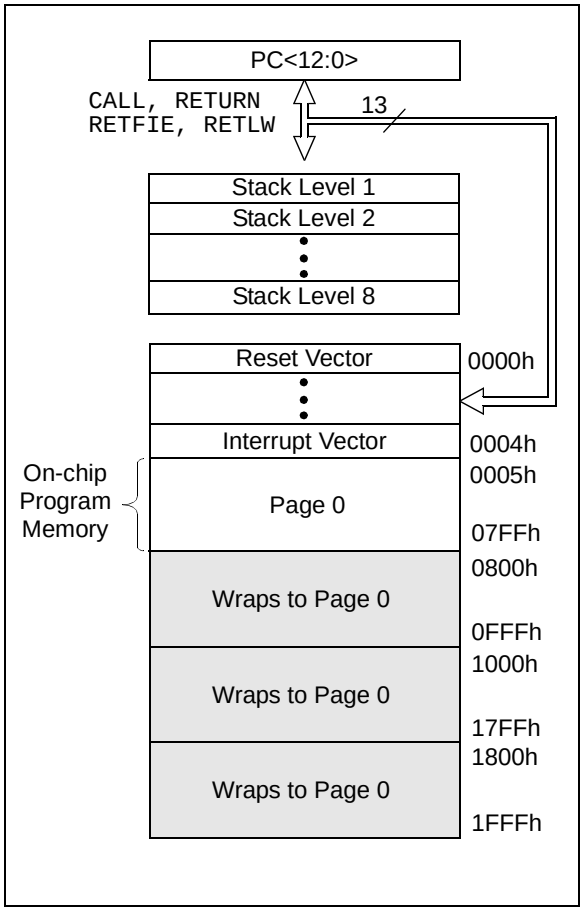
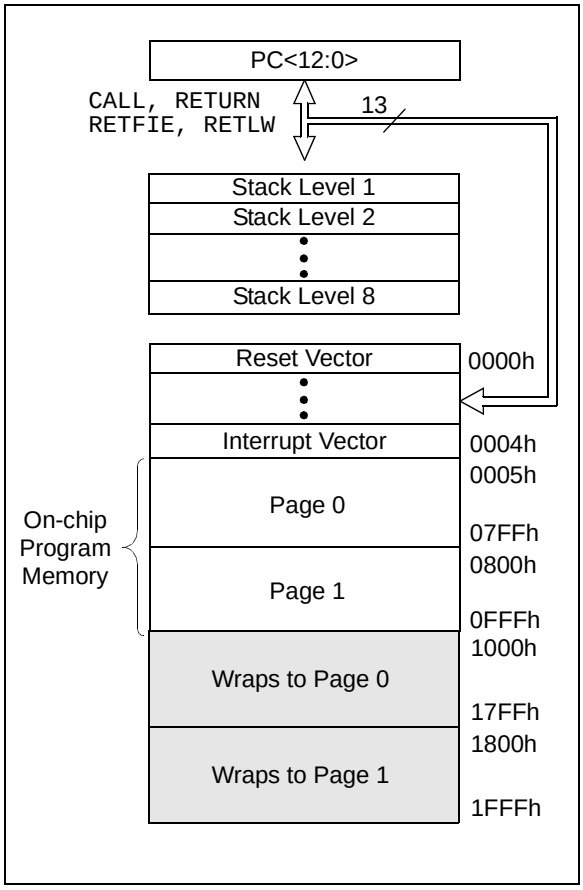


FIGURE 2-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F723/LF723 AND PIC16F724/LF724



2.2.2.3 PCON Register

The Power Control (PCON) register contains flag bits (refer to Table 3-2) to differentiate between a:

- Power-on Reset ($\overline{POR}$)
- Brown-out Reset ($\overline{BOR}$)
- Watchdog Timer Reset (WDT)
- External $\overline{MCLR}$ Reset

The PCON register also controls the software enable of the BOR.

The PCON register bits are shown in Register 2-3.

REGISTER 2-3: PCON: POWER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-q	R/W-q
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown
q = Value depends on condition			

bit 7-2 **Unimplemented:** Read as ‘0’

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
- 1 = No Power-on Reset occurred
- 0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit
- 1 = No Brown-out Reset occurred
- 0 = A Brown-out Reset occurred (must be set in software after a Power-on Reset or Brown-out Reset occurs)

Note 1: Set BOREN<1:0> = 01 in the Configuration Word register for this bit to control the $\overline{BOR}$.

3.5 Brown-Out Reset (BOR)

Brown-out Reset is enabled by programming the BOREN<1:0> bits in the Configuration register. The brown-out trip point is selectable from two trip points via the BORV bit in the Configuration register.

Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

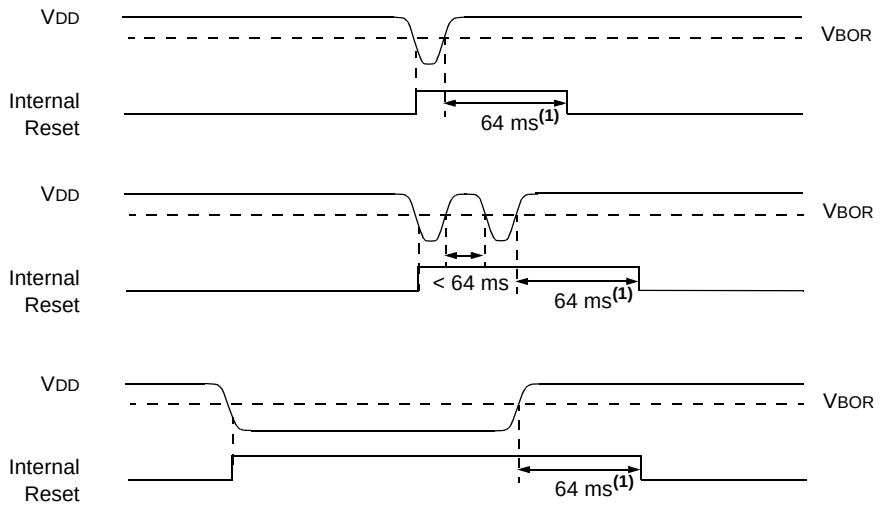
Two bits are used to enable the BOR. When BOREN = 11, the BOR is always enabled. When BOREN = 10, the BOR is enabled, but disabled during Sleep. When BOREN = 0X, the BOR is disabled.

If VDD falls below VBOR for greater than parameter (TBOR) (see **Section 23.0 "Electrical Specifications"**), the brown-out situation will reset the device. This will occur regardless of VDD slew rate. A Reset is not ensured to occur if VDD falls below VBOR for more than TBOR.

If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above VBOR, the Power-up Timer will execute a 64 ms Reset.

Note:	When erasing Flash program memory, the BOR is forced to enabled at the minimum BOR setting to ensure that any code protection circuitry is operating properly.

FIGURE 3-3: BROWN-OUT SITUATIONS



Note 1: 64 ms delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

4.5.3 PIE2 REGISTER

The PIE2 register contains the interrupt enable bits, as shown in Register 4-3.

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

REGISTER 4-3: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	CCP2IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-1 **Unimplemented:** Read as '0'

bit 0 **CCP2IE:** CCP2 Interrupt Enable bit
1 = Enables the CCP2 interrupt
0 = Disables the CCP2 interrupt

FIGURE 12-3: TIMER1 GATE COUNT ENABLE MODE

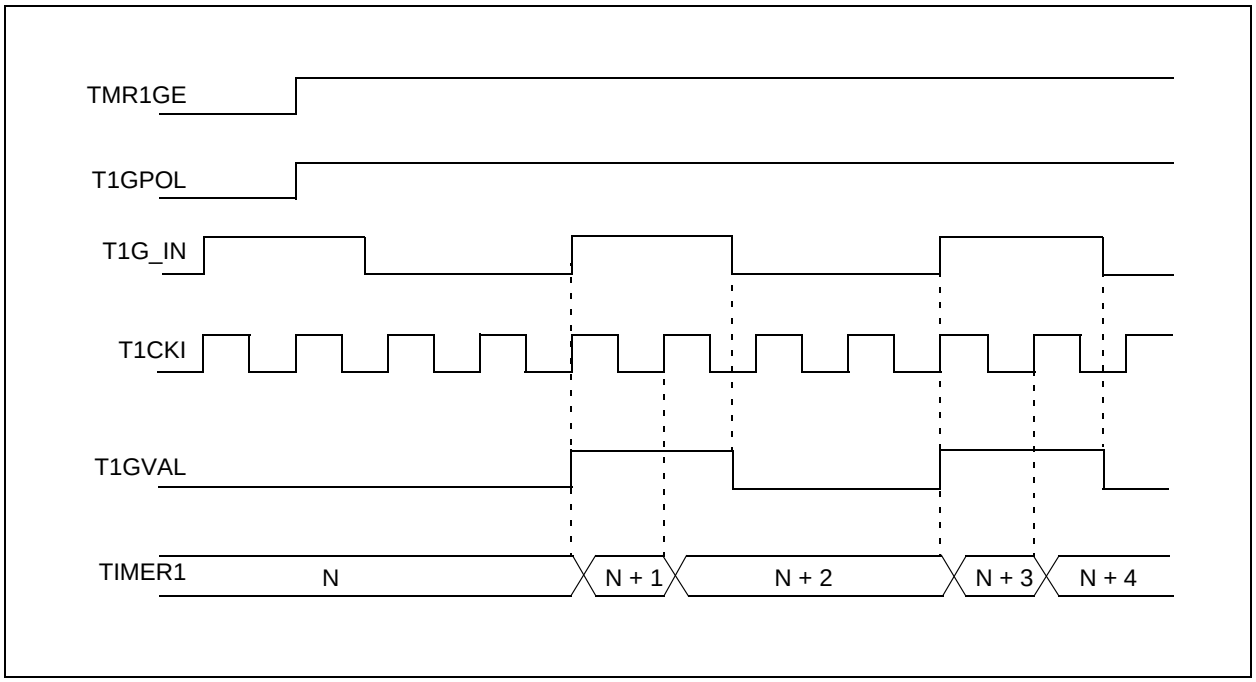
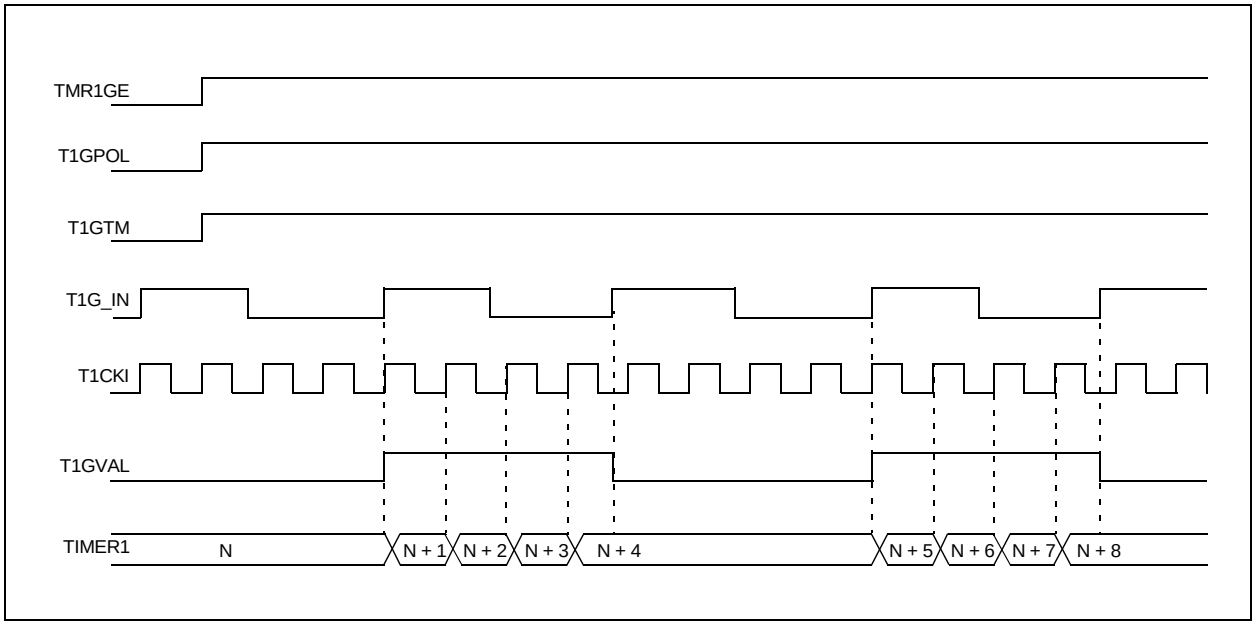


FIGURE 12-4: TIMER1 GATE TOGGLE MODE

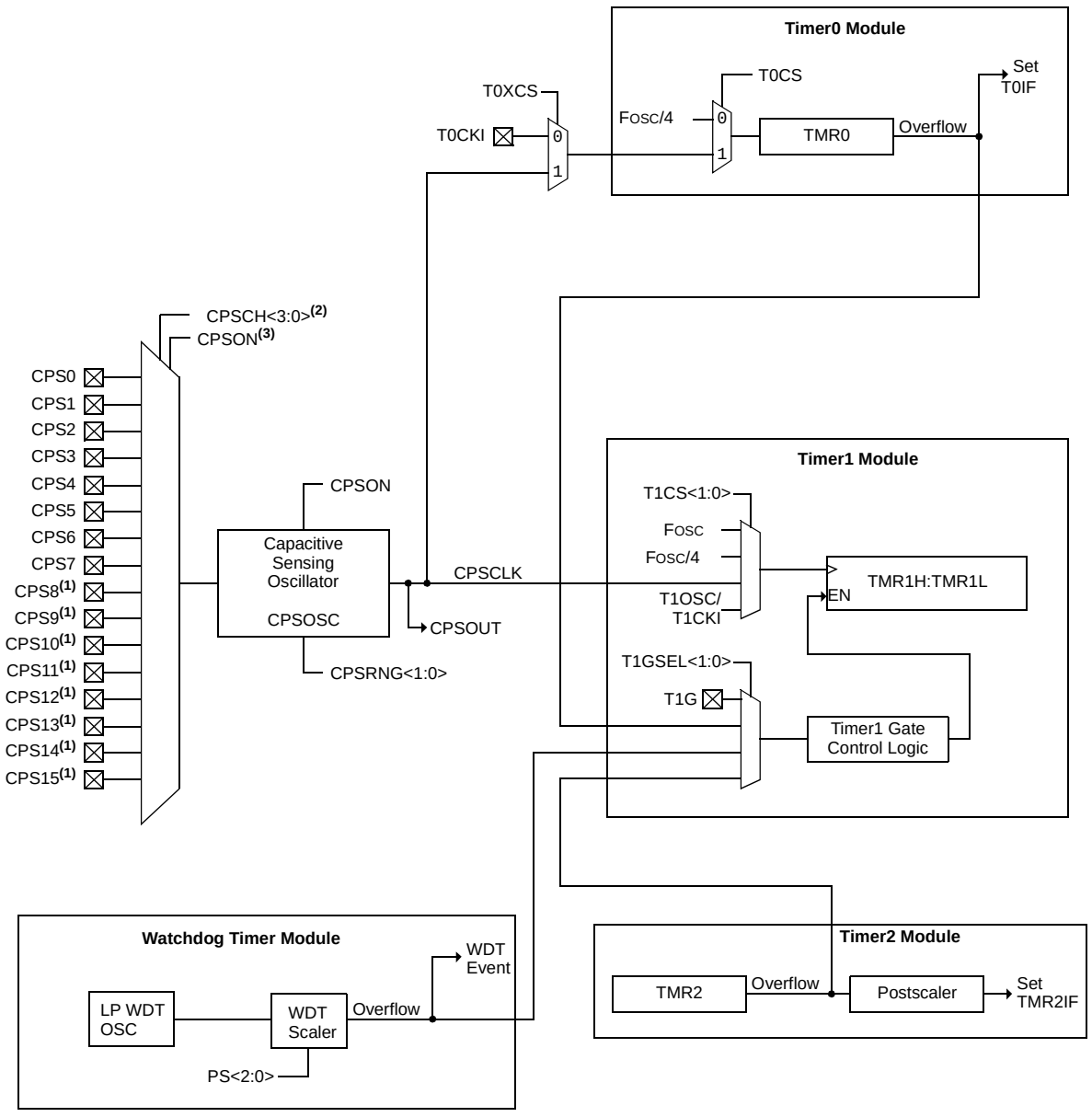


14.0 CAPACITIVE SENSING MODULE

The capacitive sensing module allows for an interaction with an end user without a mechanical interface. In a typical application, the capacitive sensing module is attached to a pad on a printed circuit board (PCB), which is electrically isolated from the end user. When the end user places their finger over the PCB pad, a capacitive load is added, causing a frequency shift in the capacitive sensing module. The capacitive sensing module requires software and at least one timer resource to determine the change in frequency. Key features of this module include:

- Analog MUX for monitoring multiple inputs
- Capacitive sensing oscillator
- Multiple timer resources
- Software control
- Operation during Sleep

FIGURE 14-1: CAPACITIVE SENSING BLOCK DIAGRAM



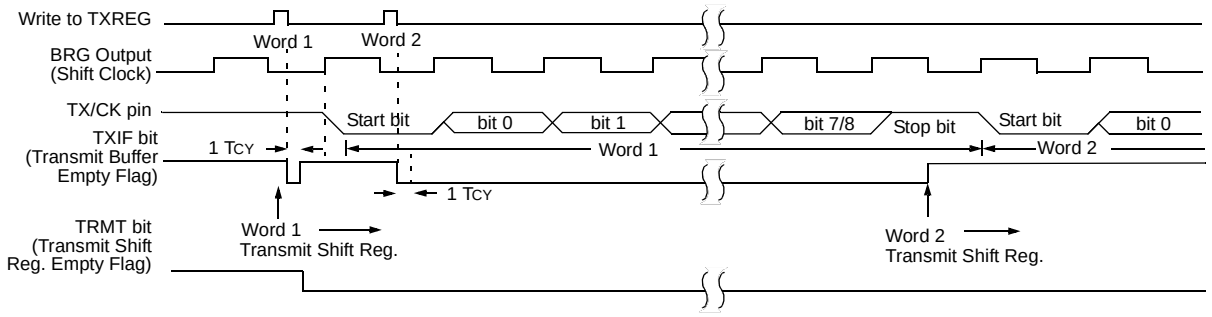
Note 1: Channels CPS<15:8> are implemented on PIC16F724/727/PIC16LF724/727 only.
2: CPSCH3 is not implemented on PIC16F722/723/726/PIC16LF722/723/726.
3: If CPSON = 0, disabling capacitive sensing, no channel is selected.

TABLE 15-7: SUMMARY OF REGISTERS ASSOCIATED WITH PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	---- --00
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000
CCPRxL	Capture/Compare/PWM Register X Low Byte								xxxx xxxx	uuuu uuuu
CCPRxH	Capture/Compare/PWM Register X High Byte								xxxx xxxx	uuuu uuuu
PR2	Timer2 Period Register								1111 1111	1111 1111
T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
TMR2	Timer2 Module Register								0000 0000	0000 0000
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: - = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the PWM.

FIGURE 16-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 16-1: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXREG	AUSART Transmit Data Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Asynchronous Transmission.

16.4 AUSART Operation During Sleep

The AUSART will remain active during Sleep only in the Synchronous Slave mode. All other modes require the system clock and therefore cannot generate the necessary signals to run the Transmit or Receive Shift registers during Sleep.

Synchronous Slave mode uses an externally generated clock to run the Transmit and Receive Shift registers.

16.4.1 SYNCHRONOUS RECEIVE DURING SLEEP

To receive during Sleep, all the following conditions must be met before entering Sleep mode:

- RCSTA and TXSTA Control registers must be configured for Synchronous Slave Reception (refer to **Section 16.3.2.4 "Synchronous Slave Reception Setup:"**).
- If interrupts are desired, set the RCIE bit of the PIE1 register and the PEIE bit of the INTCON register.
- The RCIF interrupt flag must be cleared by reading RCREG to unload any pending characters in the receive buffer.

Upon entering Sleep mode, the device will be ready to accept data and clocks on the RX/DT and TX/CK pins, respectively. When the data word has been completely clocked in by the external device, the RCIF interrupt flag bit of the PIR1 register will be set. Thereby, waking the processor from Sleep.

Upon waking from Sleep, the instruction following the SLEEP instruction will be executed. If the GIE global interrupt enable bit of the INTCON register is also set, then the Interrupt Service Routine at address 0004h will be called.

16.4.2 SYNCHRONOUS TRANSMIT DURING SLEEP

To transmit during Sleep, all the following conditions must be met before entering Sleep mode:

- RCSTA and TXSTA Control registers must be configured for Synchronous Slave Transmission (refer to **Section 16.3.2.2 "Synchronous Slave Transmission Setup:"**).
- The TXIF interrupt flag must be cleared by writing the output data to the TXREG, thereby filling the TSR and transmit buffer.
- If interrupts are desired, set the TXIE bit of the PIE1 register and the PEIE bit of the INTCON register.

Upon entering Sleep mode, the device will be ready to accept clocks on TX/CK pin and transmit data on the RX/DT pin. When the data word in the TSR has been completely clocked out by the external device, the pending byte in the TXREG will transfer to the TSR and the TXIF flag will be set. Thereby, waking the processor from Sleep. At this point, the TXREG is available to accept another character for transmission, which will clear the TXIF flag.

Upon waking from Sleep, the instruction following the SLEEP instruction will be executed. If the GIE global interrupt enable bit is also set then the Interrupt Service Routine at address 0004h will be called.

REGISTER 17-1: SSPCON: SYNC SERIAL PORT CONTROL REGISTER (SPI MODE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **WCOL**: Write Collision Detect bit
- 1 = The SSPBUF register is written while it is still transmitting the previous word (must be cleared in software)
- 0 = No collision

bit 6 **SSPOV**: Receive Overflow Indicator bit
- 1 = A new byte is received while the SSPBUF register is still holding the previous data. In case of overflow, the data in SSPSR is lost. Overflow can only occur in Slave mode. The user must read the SSPBUF, even if only transmitting data, to avoid setting overflow. In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPBUF register.
- 0 = No overflow

bit 5 **SSPEN**: Synchronous Serial Port Enable bit
- 1 = Enables serial port and configures SCK, SDO and SDI as serial port pins**(1)**
- 0 = Disables serial port and configures these pins as I/O port pins

bit 4 **CKP**: Clock Polarity Select bit
- 1 = Idle state for clock is a high level
- 0 = Idle state for clock is a low level

bit 3-0 **SSPM<3:0>**: Synchronous Serial Port Mode Select bits
- 0000 = SPI Master mode, clock = FOSC/4
- 0001 = SPI Master mode, clock = FOSC/16
- 0010 = SPI Master mode, clock = FOSC/64
- 0011 = SPI Master mode, clock = TMR2 output/2
- 0100 = SPI Slave mode, clock = SCK pin. $\overline{SS}$ pin control enabled.
- 0101 = SPI Slave mode, clock = SCK pin. $\overline{SS}$ pin control disabled. $\overline{SS}$ can be used as I/O pin.

Note 1: When enabled, these pins must be properly configured as input or output.

17.2.7 CLOCK STRETCHING

During any SCL low phase, any device on the I^2C bus may hold the SCL line low and delay, or pause, the transmission of data. This “stretching” of a transmission allows devices to slow down communication on the bus. The SCL line must be constantly sampled by the master to ensure that all devices on the bus have released SCL for more data.

Stretching usually occurs after an $\overline{ACK}$ bit of a transmission, delaying the first bit of the next byte. The SSP module hardware automatically stretches for two conditions:

- After a 10-bit address byte is received (update SSPADD register)
- Anytime the CKP bit of the SSPCON register is cleared by hardware

The module will hold SCL low until the CKP bit is set. This allows the user slave software to update SSPBUF with data that may not be readily available. In 10-bit addressing modes, the SSPADD register must be updated after receiving the first and second address bytes. The SSP module will hold the SCL line low until the SSPADD has a byte written to it. The UA bit of the SSPSTAT register will be set, along with SSPIF, indicating an address update is needed.

17.2.8 FIRMWARE MASTER MODE

Master mode of operation is supported in firmware using interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits of the SSPSTAT register are cleared from a Reset or when the SSP module is disabled (SSPEN cleared). The Stop (P) and Start (S) bits will toggle based on the Start and Stop conditions. Control of the I^2C bus may be taken when the P bit is set or the bus is Idle and both the S and P bits are clear.

In Firmware Master mode, the SCL and SDA lines are manipulated by setting/clearing the corresponding TRIS bit(s). The output level is always low, irrespective of the value(s) in the corresponding PORT register bit(s). When transmitting a ‘1’, the TRIS bit must be set (input) and a ‘0’, the TRIS bit must be clear (output).

The following events will cause the SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt will occur if enabled):

- Start condition
- Stop condition
- Data transfer byte transmitted/received

Firmware Master Mode of operation can be done with either the Slave mode Idle (SSPM<3:0> = 1011), or with either of the Slave modes in which interrupts are enabled. When both master and slave functionality is enabled, the software needs to differentiate the source(s) of the interrupt.

Refer to Application Note *AN554, Software Implementation of I^2C™ Bus Master* (DS00554) for more information.

17.2.9 MULTI-MASTER MODE

In Multi-Master mode, the interrupt generation on the detection of the Start and Stop conditions allow the determination of when the bus is free. The Stop (P) and Start (S) bits are cleared from a Reset or when the SSP module is disabled. The Stop (P) and Start (S) bits will toggle based on the Start and Stop conditions. Control of the I^2C bus may be taken when the P bit of the SSPSTAT register is set or when the bus is Idle, and both the S and P bits are clear. When the bus is busy, enabling the SSP Interrupt will generate the interrupt when the Stop condition occurs.

In Multi-Master operation, the SDA line must be monitored to see if the signal level is the expected output level. This check only needs to be done when a high level is output. If a high level is expected and a low level is present, the device needs to release the SDA and SCL lines (set TRIS bits). There are two stages where this arbitration of the bus can be lost. They are the Address Transfer and Data Transfer stages.

When the slave logic is enabled, the slave continues to receive. If arbitration was lost during the address transfer stage, communication to the device may be in progress. If addressed, an $\overline{ACK}$ pulse will be generated. If arbitration was lost during the data transfer stage, the device will need to re-transfer the data at a later time.

Refer to Application Note *AN578, Use of the SSP Module in the I^2C™ Multi-Master Environment* (DS00578) for more information.

21.0 INSTRUCTION SET SUMMARY

The PIC16(L)F722/3/4/6/7 instruction set is highly orthogonal and is comprised of three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

Each PIC16 instruction is a 14-bit word divided into an **opcode,** which specifies the instruction type and one or more **operands,** which further specify the operation of the instruction. The formats for each of the categories is presented in Figure 21-1, while the various opcode fields are summarized in Table 21-1.

Table 21-2 lists the instructions recognized by the MPASM™ assembler.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator, which selects the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8-bit or 11-bit constant, or literal value.

One instruction cycle consists of four oscillator periods; for an oscillator frequency of 4 MHz, this gives a nominal instruction execution time of 1 µs. All instructions are executed within a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of an instruction. When this occurs, the execution takes two instruction cycles, with the second cycle executed as a NOP.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

21.1 Read-Modify-Write Operations

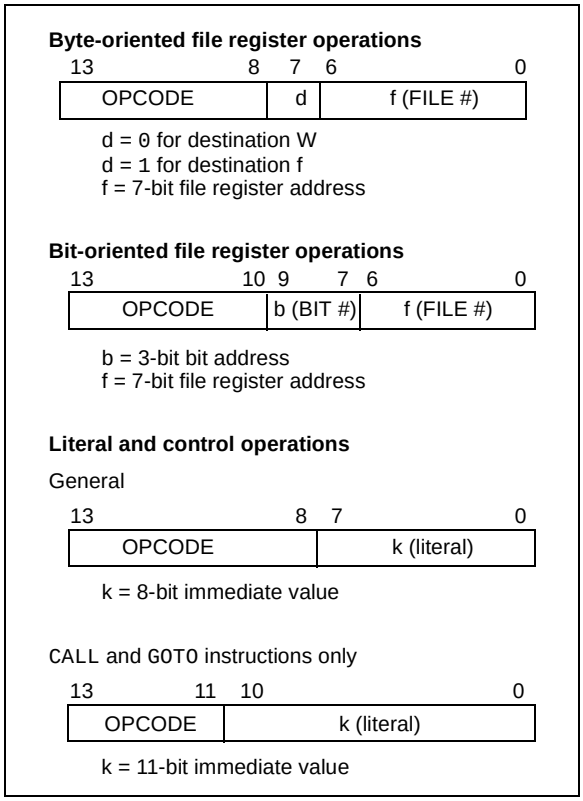
Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

For example, a CLRF PORTB instruction will read PORTB, clear all the data bits, then write the result back to PORTB. This example would have the unintended consequence of clearing the condition that set the RBIF flag.

TABLE 21-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
PC	Program Counter
$\overline{TO}$	Time-out bit
C	Carry bit
DC	Digit carry bit
Z	Zero bit
$\overline{PD}$	Power-down bit

FIGURE 21-1: GENERAL FORMAT FOR INSTRUCTIONS



22.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

22.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

23.5 Thermal Considerations

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θJA	Thermal Resistance Junction to Ambient	60	°C/W	28-pin SPDIP package
			80	°C/W	28-pin SOIC package
			90	°C/W	28-pin SSOP package
			27.5	°C/W	28-pin UQFN 4x4mm package
			27.5	°C/W	28-pin QFN 6x6mm package
			47.2	°C/W	40-pin PDIP package
			46	°C/W	44-pin TQFP package
			24.4	°C/W	44-pin QFN 8x8mm package
TH02	θJC	Thermal Resistance Junction to Case	31.4	°C/W	28-pin SPDIP package
			24	°C/W	28-pin SOIC package
			24	°C/W	28-pin SSOP package
			24	°C/W	28-pin UQFN 4x4mm package
			24	°C/W	28-pin QFN 6x6mm package
			24.7	°C/W	40-pin PDIP package
			14.5	°C/W	44-pin TQFP package
			20	°C/W	44-pin QFN 8x8mm package
TH03	TJMAX	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = PINTERNAL + PI/O
TH05	PINTERNAL	Internal Power Dissipation	—	W	PINTERNAL = IDD x VDD(1)
TH06	PI/O	I/O Power Dissipation	—	W	PI/O = Σ (IOL * VOL) + Σ (IOH * (VDD - VOH))
TH07	PDER	Derated Power	—	W	PDER = PDMAX (TJ - TA)/θJA(2)

Note 1: IDD is current to run the chip alone without driving any load on the output pins.
2: TA = Ambient Temperature
3: TJ = Junction Temperature

TABLE 23-1: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS01	FOSC	External CLKIN Frequency(1)	DC	—	37	kHz	LP Oscillator mode
			DC	—	4	MHz	XT Oscillator mode
			DC	—	20	MHz	HS Oscillator mode
			DC	—	20	MHz	EC Oscillator mode
		Oscillator Frequency(1)	—	32.768	—	kHz	LP Oscillator mode
			0.1	—	4	MHz	XT Oscillator mode
			1	—	20	MHz	HS Oscillator mode
			DC	—	4	MHz	RC Oscillator mode
OS02	TOSC	External CLKIN Period(1)	27	—	∞	µs	LP Oscillator mode
			250	—	∞	ns	XT Oscillator mode
			50	—	∞	ns	HS Oscillator mode
			50	—	∞	ns	EC Oscillator mode
		Oscillator Period(1)	—	30.5	—	µs	LP Oscillator mode
			250	—	10,000	ns	XT Oscillator mode
			50	—	1,000	ns	HS Oscillator mode
			250	—	—	ns	RC Oscillator mode
OS03	TCY	Instruction Cycle Time(1)	200	TCY	DC	ns	TCY = 4/FOSC
OS04*	TosH, TosL	External CLKIN High, External CLKIN Low	2	—	—	µs	LP oscillator
			100	—	—	ns	XT oscillator
			20	—	—	ns	HS oscillator
OS05*	TosR, TosF	External CLKIN Rise, External CLKIN Fall	0	—	∞	ns	LP oscillator
			0	—	∞	ns	XT oscillator
			0	—	∞	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min” values with an external clock applied to OSC1 pin. When an external clock input is used, the “max” cycle time limit is “DC” (no clock) for all devices.

TABLE 23-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±2%	—	16.0	—	MHz	0°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			±5%	—	16.0	—	MHz	-40°C ≤ TA ≤ +125°C
OS08A	MFOSC	Internal Calibrated MFINTOSC Frequency(2)	±2%	—	500	—	kHz	0°C ≤ TA ≤ +85°C VDD ≥ 2.5V
			±5%	—	500	10	kHz	-40°C ≤ TA ≤ +125°C
OS10*	TIOSC ST	HFINTOSC Wake-up from Sleep Start-up Time	—	—	5	8	µs	
		MFINTOSC Wake-up from Sleep Start-up Time	—	—	20	30	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

3: By design.

FIGURE 23-7: CLKOUT AND I/O TIMING

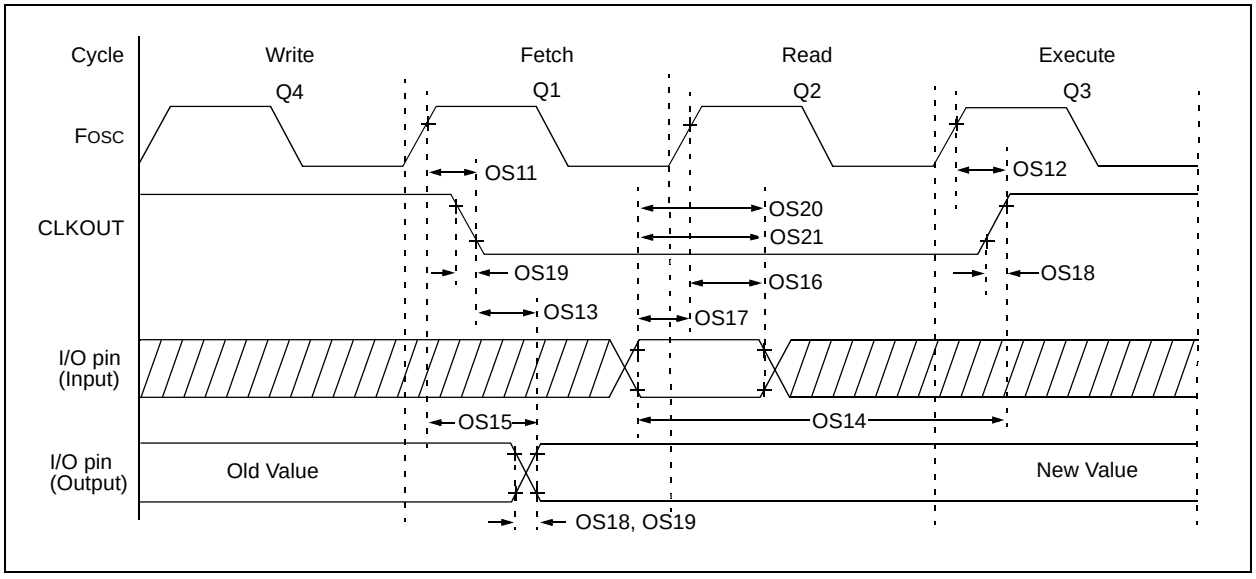


FIGURE 24-55: VOL VS. IOL OVER TEMPERATURE, VDD = 5.5V

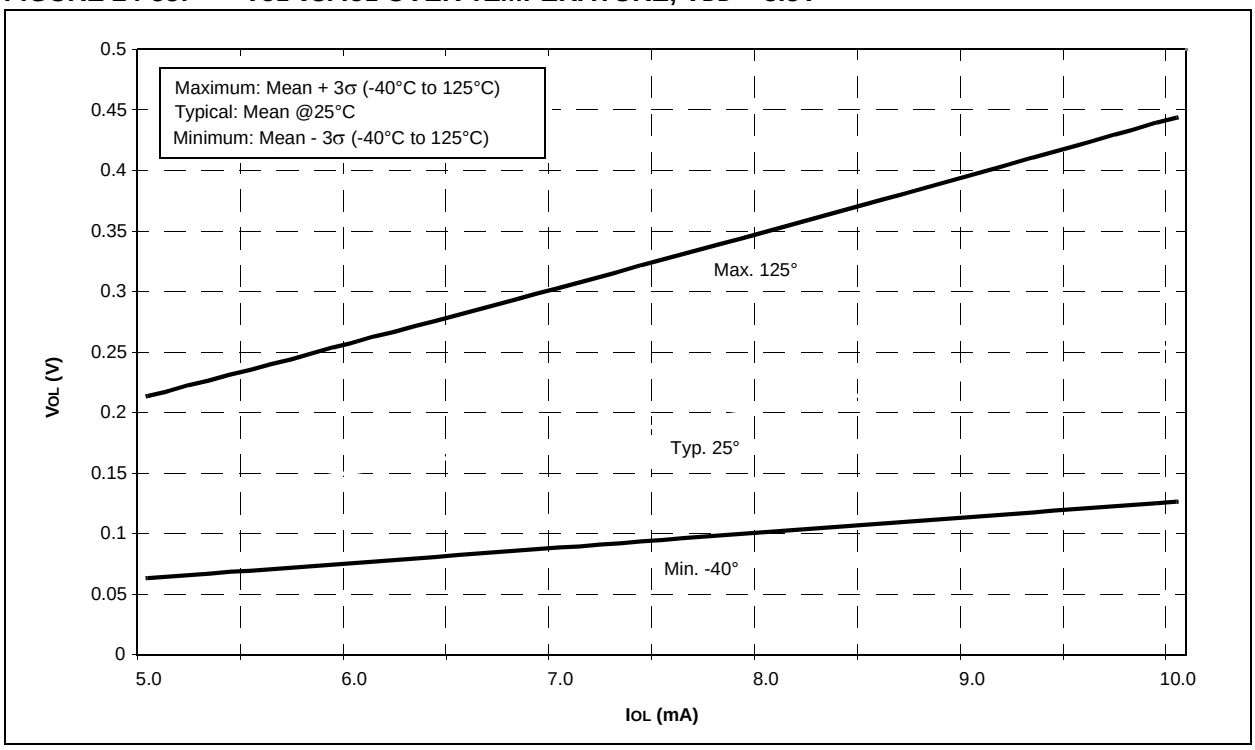
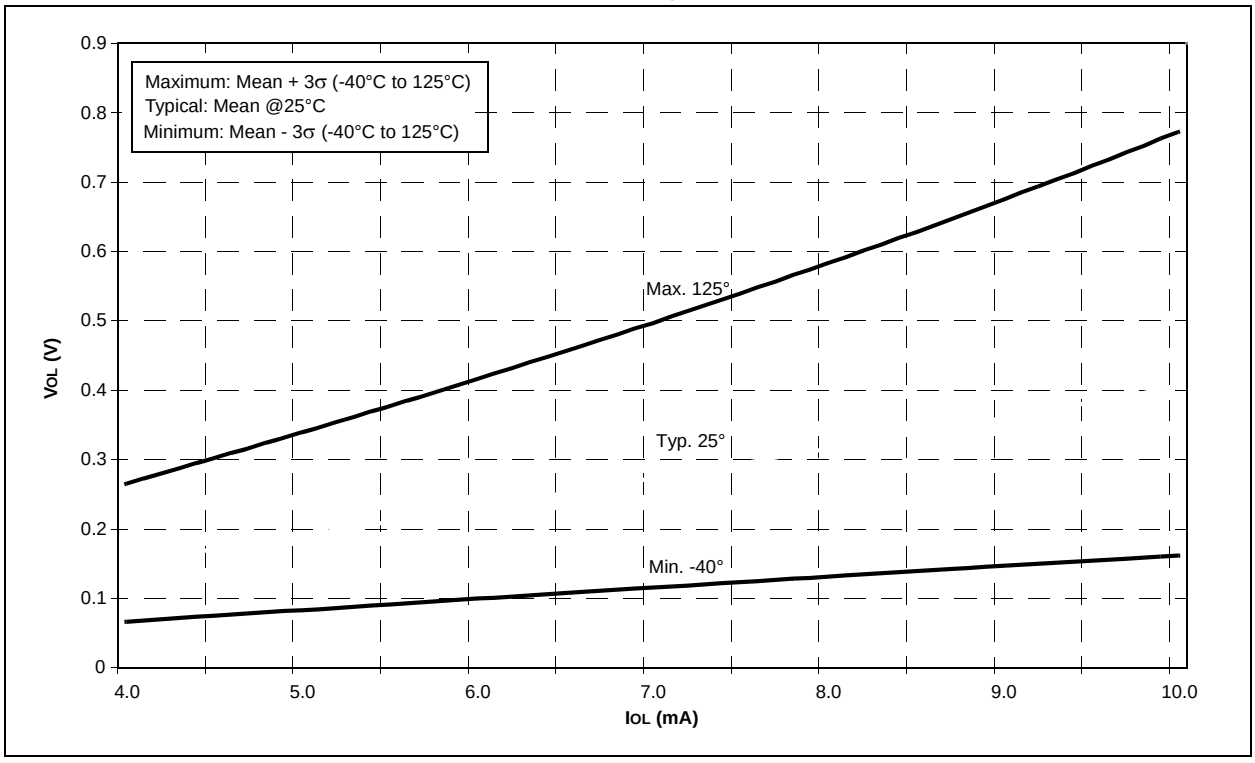


FIGURE 24-56: VOL VS. IOL OVER TEMPERATURE, VDD = 3.6V



PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	X	/XX	XXX
Device	Tape and Reel Option	Temperature Range	Package	Pattern

Device:	PIC16F722, PIC16LF722, PIC16F722T, PIC16LF722T(1) PIC16F723, PIC16LF723, PIC16F723T, PIC16LF723T(1) PIC16F724, PIC16LF724, PIC16F724T, PIC16LF724T(1) PIC16F726, PIC16LF726, PIC16F726T, PIC16LF726T(1) PIC16F727, PIC16LF727, PIC16F727T, PIC16LF727T(1)	
Tape and Reel Option:	I = -40°C to +85°C E = -40°C to +125°C MV = Micro Lead Frame (UQFN)	
Temperature Range:	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)	
Package:	ML = Micro Lead Frame (QFN) P = Plastic DIP PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny Plastic DIP SS = SSOP	

Examples:

a) PIC16F722-E/SP 301 = Extended Temp., skinny PDIP package, QTP pattern #301

b) PIC16F722-I/SO = Industrial Temp., SOIC package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.